

Editorial

Preface: The Second International Congress on Technology and Innovation in Engineering and Computing [†]

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[†] All proceeding papers published in this volume are presented at the II International Congress on Technology and Innovation in Engineering and Computing, Online, 21–25 November 2022.

1. Introduction

Due to the context in which we find ourselves, today more than ever we must think globally about the growth and development of our society. Now is the time when the impact of the practices of Engineering and Computer Science in the field of technology, innovation and sustainability takes prominence. Participate in this event and discover the solutions that Engineering offers different fields. We are waiting for you to join us!

2. Conference Theme

2.1. Computer Science/Information Systems

This theme will show the application of the different areas of knowledge of Computer Science and Information Systems to the productive, entertainment and health sectors. The vision is oriented to the creation and development of a proprietary technology to reduce the consumption of those that already exist.

2.2. Digital Manufacturing, Robotics, Electronic Systems and Automation

The national and international industrial experience brings to mind several considerations regarding automation projects. Currently, it is necessary to define a digital strategy to guide us towards the successful implementation of digital transformation in an organization, recognizing the opportunities created by new technologies.

The technological progress along the stages of automation in the productive sphere will be reviewed, with an emphasis on robotics, electronic systems and automation.

2.3. Environment and Sustainability

We are at a historic milestone for humanity in which we must think globally and apply science and technology to achieve the United Nations' sustainable development goals. Under this approach, economic growth and development are linked to responsible production and consumption, committed to the efficient use of energy and environmental conservation.

The focus will be on new efficient technologies that seek to reduce environmental impact.

2.4. Physical and Building Systems

A country's capacity to meet the needs of its population depends on its infrastructure in each of the key areas: health, education, transportation, production and communication. And not just in terms of the number of hospitals, schools or kilometers of roads, but also in terms of quality and efficiency. Therefore, the conference will review new materials, techniques and technologies in engineering and computing that allow this infrastructure to be constructed and maintained more efficiently and, therefore, to better serve society.



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2.5. Emerging Materials

Currently, given the global problem of scarcity of resources, society has been forced to implement new materials in different industries. The use of digital technologies in the ideation process, as well as their application in engineering, will be studied in depth.

2.6. Food Science

The objective is to provide advances in new emerging processing technologies, with an emphasis on obtaining functional foods/ingredients and nutraceuticals, innovative models, industry 4.0, marketing and regulation, applicable to food development.

3. Topics, Committees

3.1. Call for Papers

We invite the academic, scientific and research community in Engineering and Computer Science to submit abstracts within the thematic axes that are part of the congress.

3.1.1. Submission of Papers

Submit a short abstract in English (300 words) by 31 October 2022.

3.1.2. Evaluation

The Scientific Committee will evaluate all abstracts submitted and authors will be notified by 7 November 2022 of acceptance. Submitted papers must not be published or under review in any other national or international conference or publication.

3.1.3. Invitation

Authors of accepted abstracts will be invited to submit proceedings papers by 20 November 2022 (maximum six pages, in the template that will be sent by mail).

3.1.4. Presentation

All accepted papers will be presented during the conference orally and online for 50 min (21–25 November 2022). After the conference, they will remain available online for reading on the congress website.

3.1.5. Publication

All accepted proceedings papers will be published in *Engineering Proceedings* (<https://www.mdpi.com/journal/engproc>) or *Computer Sciences & Mathematics Forum* (<https://www.mdpi.com/journal/csmf>), depending on the topic of the paper.

3.2. Committee

Prof. Dr. Luis Olivera-Montenegro (President)

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4. Speakers**PhD. Jaime Yañez****Peru**

PhD in Pharmacology and Toxicology, with a focus in Pharmacokinetics and Pharmacodynamics from Washington State University (WSU), B.Sc. in Food Science and Toxicology, with a specialization in Chemistry from the University of Idaho (UI). He has over 20 years of professional experience in the public and private sector.

PhD. Arturo Mariño**Peru**

Researcher in Sustainable Energy Development and teaching assistant in the programs: MBA of Hakey School of Business, School of Public Policy and MSc. Sustainable Energy Development, University of Calgary, Canada.

PhD. Jose Luis Zarate**Canada**

Electronics Development Engineer at Neura Robotics, Germany. He has worked as a research assistant at Technische Universität Ilmenau, Germany. He is Doctor of Philosophy in Biomechatronics from Technische Universität Ilmenau, Germany, Master in Mechatronics Engineering from PUCP and Technische Universität Ilmenau, and Electrical and Electronic Engineer from Pontificia Universidad Católica del Perú.

PhD. Holger Lovon**Germany**

Civil Engineer from UNSAAC, PhD in Civil Engineering from the University of Aveiro (Portugal) and Master in Civil Engineering from PUCP. He has developed research in seismic risk analysis and numerical modeling using finite and discrete elements. He has publications in scientific journals and international conferences.

5. Sponsors

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